Tool ID: 425
Tool Location: 137

Equipment Information Sheet

GCA 6300 DSW 5X g-line Wafer Stepper

Manager: Garry Bordonaro 607-254-4936
Backup: Giovanni Sartorello 607-254-4853
Backup: Michael Skvarla 607-254-4674

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during normal operation

USAGE RESTRICTIONS

- No buddy system restrictions imposed on normal operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- Maximum 3 hour block reservations during daytime
- Maximum 12 hours reserved in advance at any time per person
- No consecutive research group reservations
- Users/Groups may use any amount of unreserved time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Substrate thickness must be matched to proper chuck thickness
- Back of substrate must be CLEAN - NO RESIST on back
- Mask must be CLEAN - no resist or fingerprints
- Use Transparent/Opaque switch in proper mode (>2um SiO2, or glass, etc.)

Last Updated: 02/18/2025